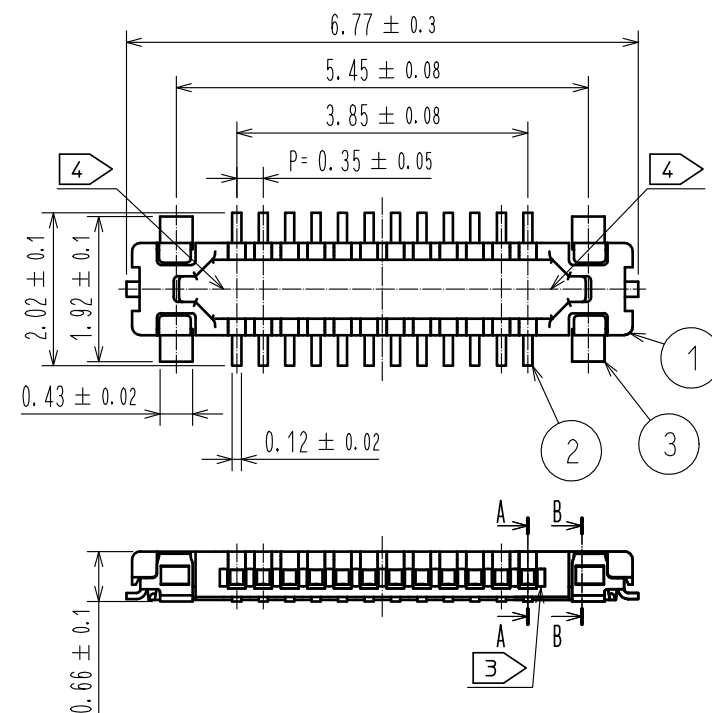


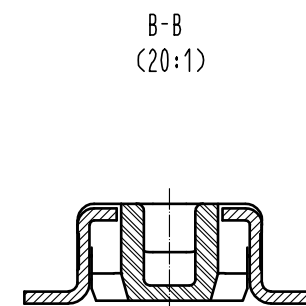
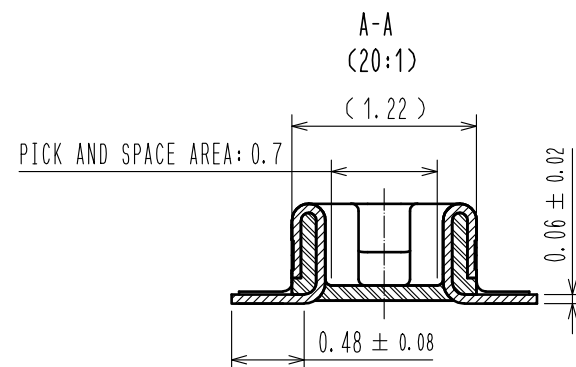


NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.

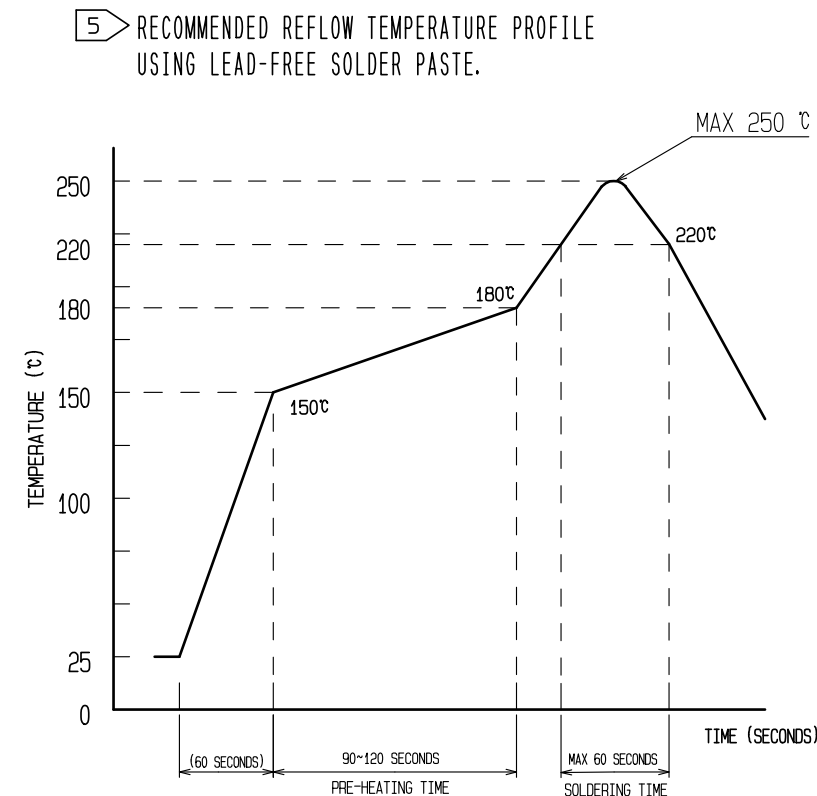
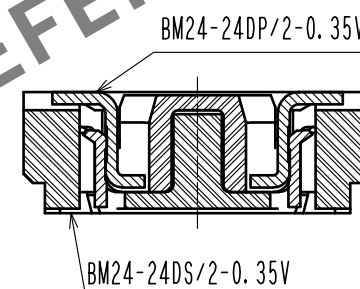
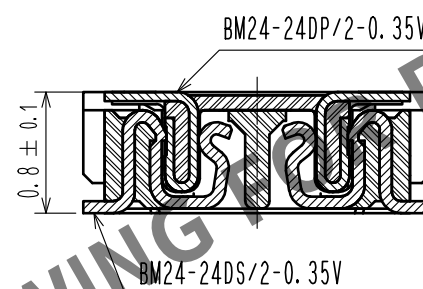
- 2 CONTACT PLATING SPECIFICATIONS
- | | |
|---------------|-------------------------------|
| CONTACT AREA | : GOLD 0.05 μm MIN |
| SMT LEAD | : GOLD 0.05 μm MIN |
| UNDER PLATING | : NICKEL 1 μm MIN |
| (SURFACE | : SEALING) |

- 3 A PART OF THE WALL COULD BE NOTCHED.

- 4 HRS MARK AND CAV No. ARE INDICATED IN APPROX. POSITION SHOWN.



ENGAGEMENT FIGURE (20:1)



REFLOW METHOD:IR REFLOW

NUMBER OF REFLOW CYCLES:2 CYCLES MAX.

- 1)REFLOW TIME

DURATION ABOVE 220°C, 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)

- 2)PRE-HEAT TIME

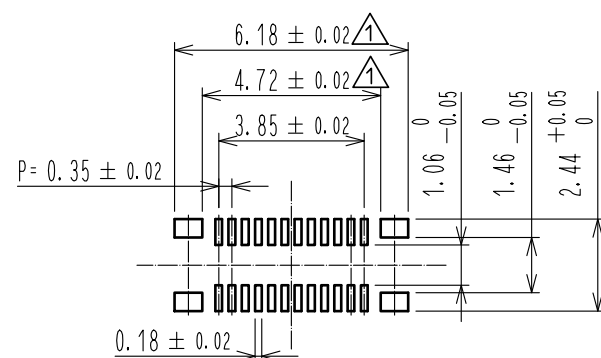
PRE-HEAT TEMPERATURE(MIN):150℃

PRE-HEAT TEMPERATURE(MAX):180℃

PRE-HEAT TIME:90-120 SEC.

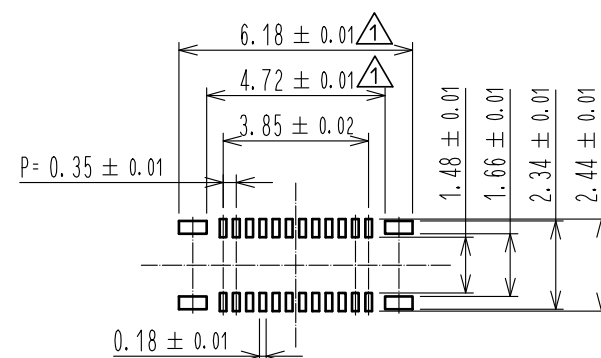
- 5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING COONDITION IS REQUIRED PRIOR TO PRODUCTION. TEPERATURE IS MEASURED AT CONTACT LEAD.
6. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

◆RECOMMENDED PCB LAYOUT



◆RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm

[illegible]

